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(12) **United States Design Patent**
Lee

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(54) **HEADPHONE**

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(**) Term: **14 Years**

(21) Appl. No.: **29/280,998**

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(51) **LOC (8) Cl.** **14-01**

(52) **U.S. Cl.** **D14/205**

(58) **Field of Classification Search** D14/205,
D14/206, 223, 137, 192; 181/129, 130, 137;
381/309, 370, 374, 380, 381; 379/430; D29/112;
2/209

See application file for complete search history.

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Primary Examiner—Paula A Greene

(57) **CLAIM**

The ornamental design for a headphone, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a headphone showing my new design, the undisclosed interior ear portion is not part of the claimed design;

FIG. 2 is a front elevational view thereof;

FIG. 3 is a rear elevational view thereof;

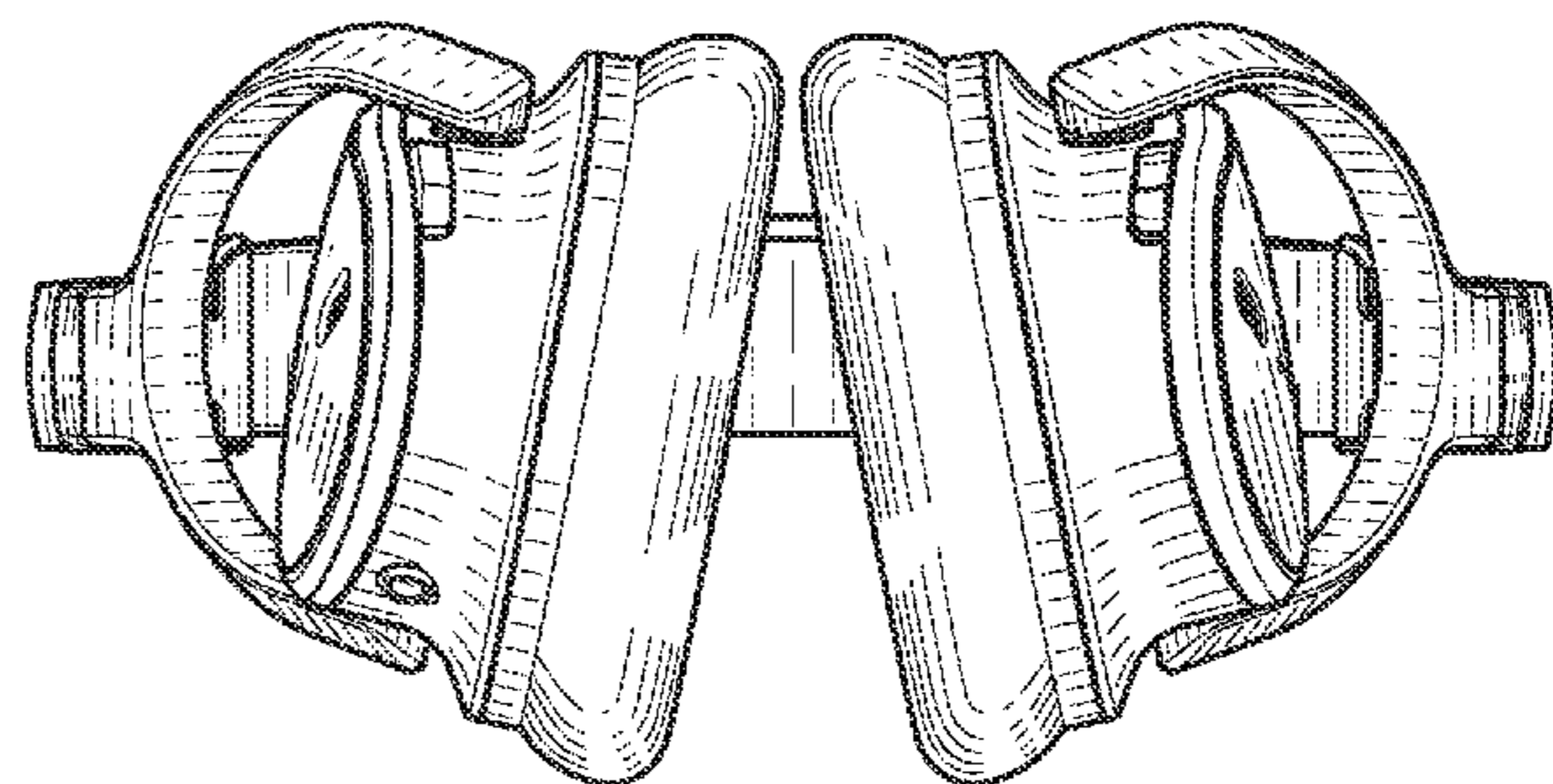
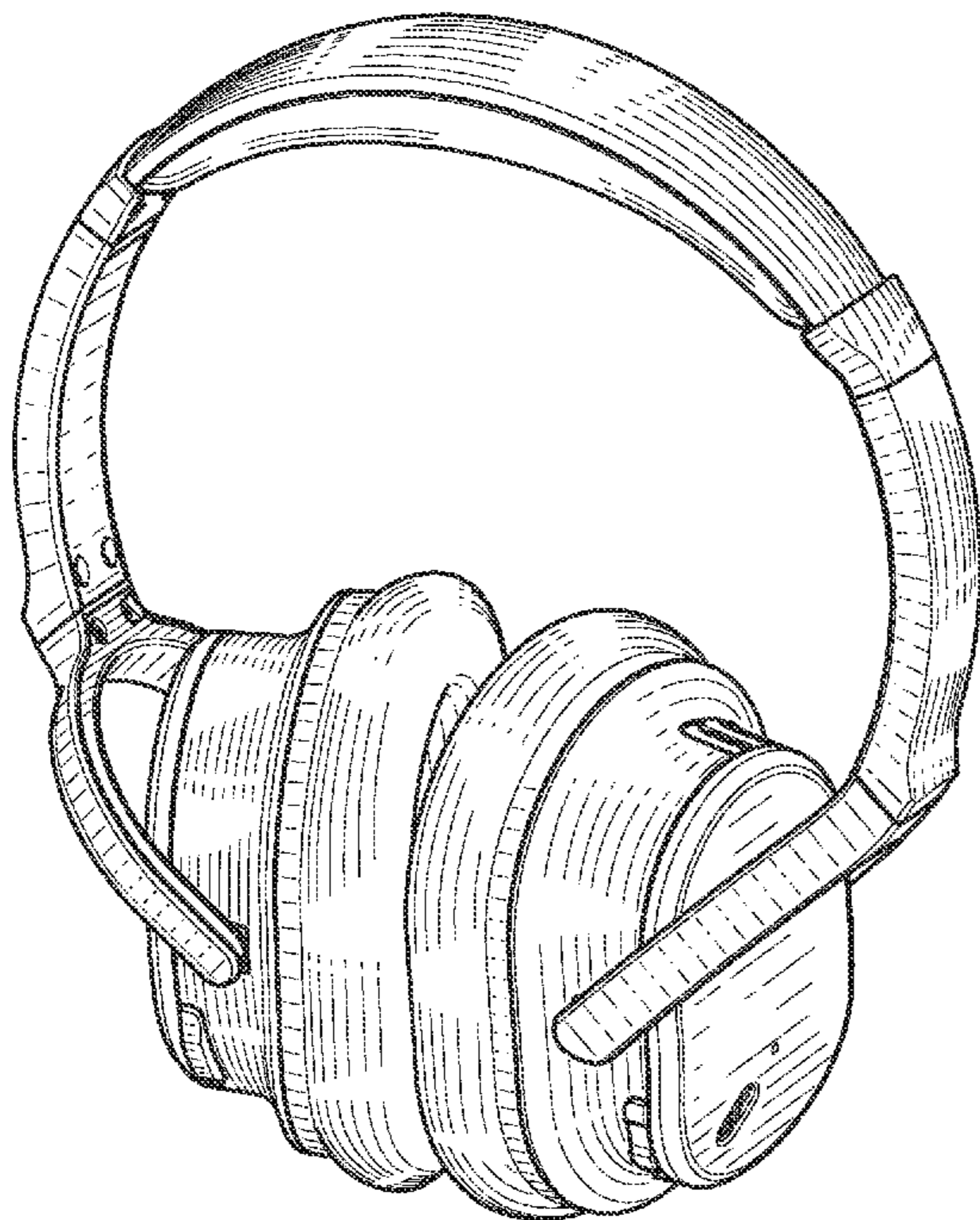
FIG. 4 is a right side elevational view thereof;

FIG. 5 is a left side elevational view thereof;

FIG. 6 is a top plan view thereof; and,

FIG. 7 is a bottom plan view thereof.

1 Claim, 5 Drawing Sheets



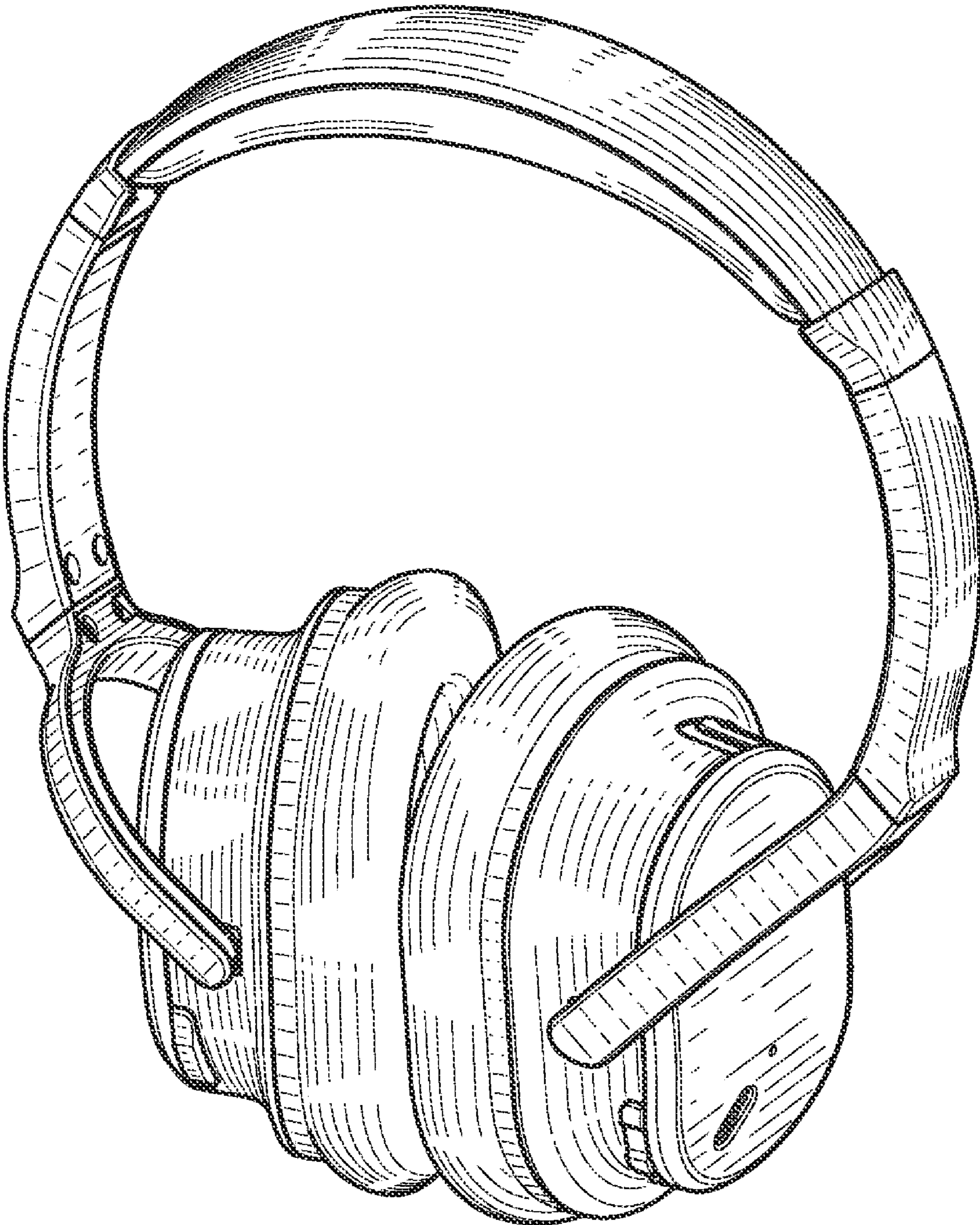


FIG. 1

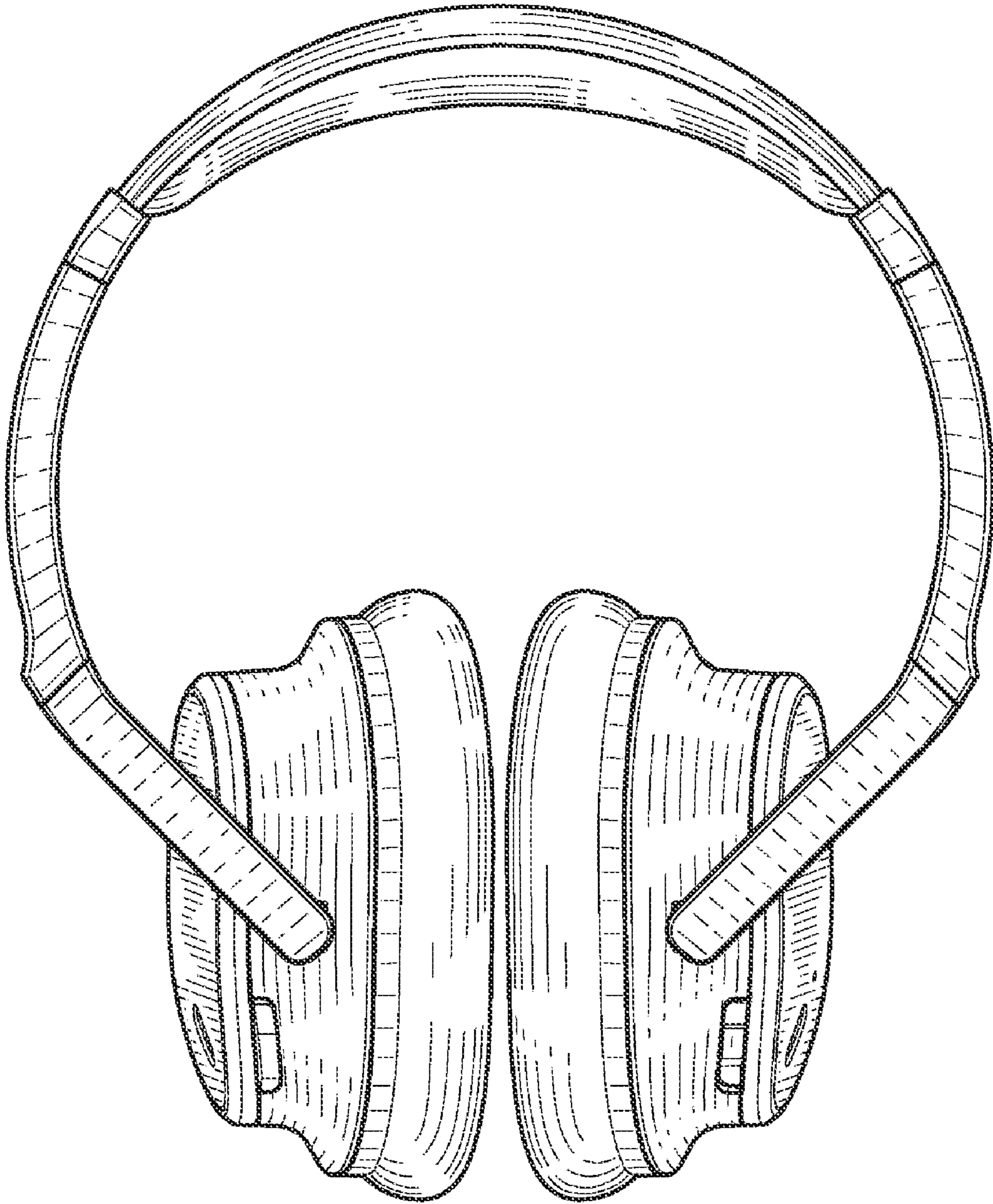


FIG. 2

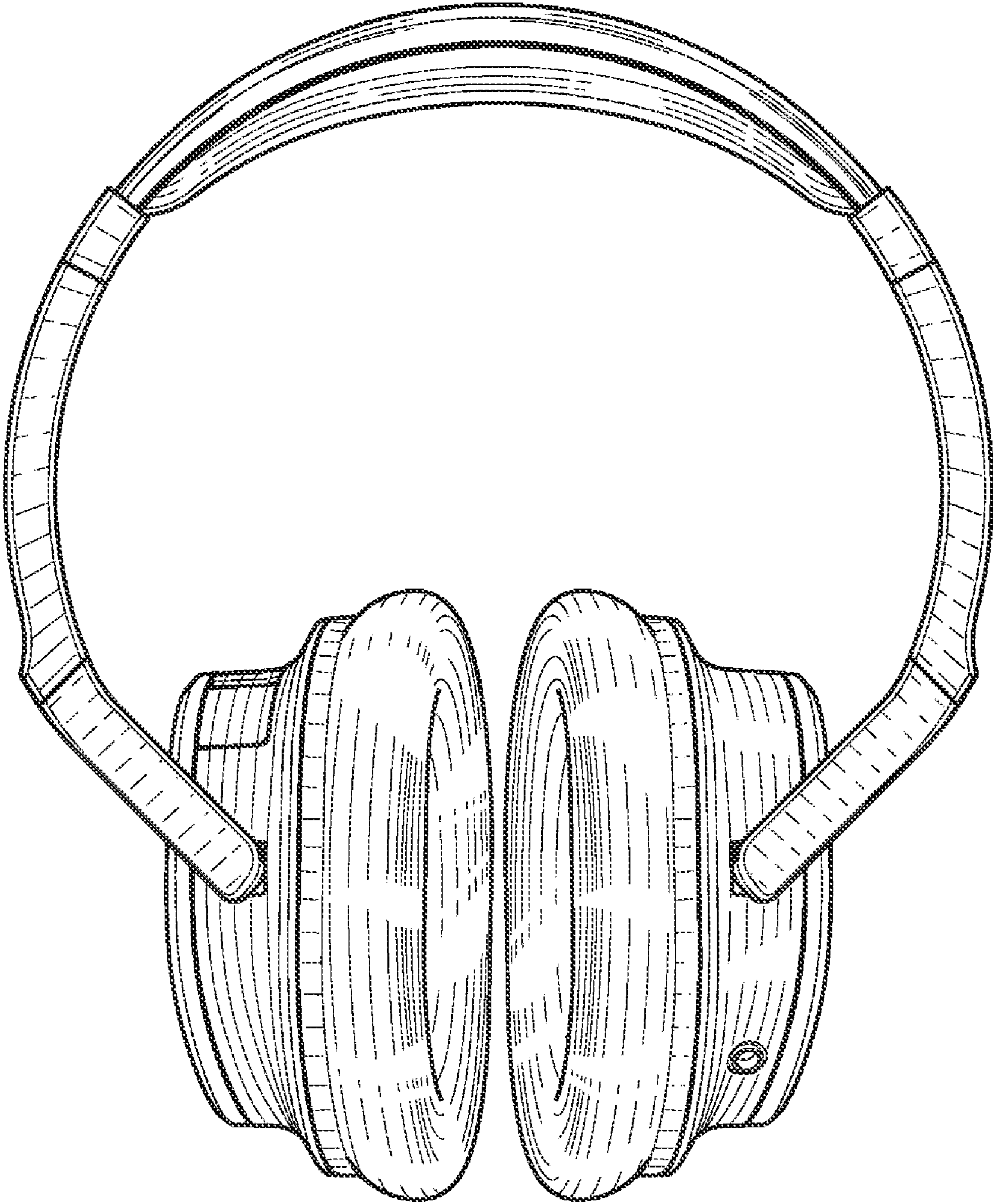


FIG. 3

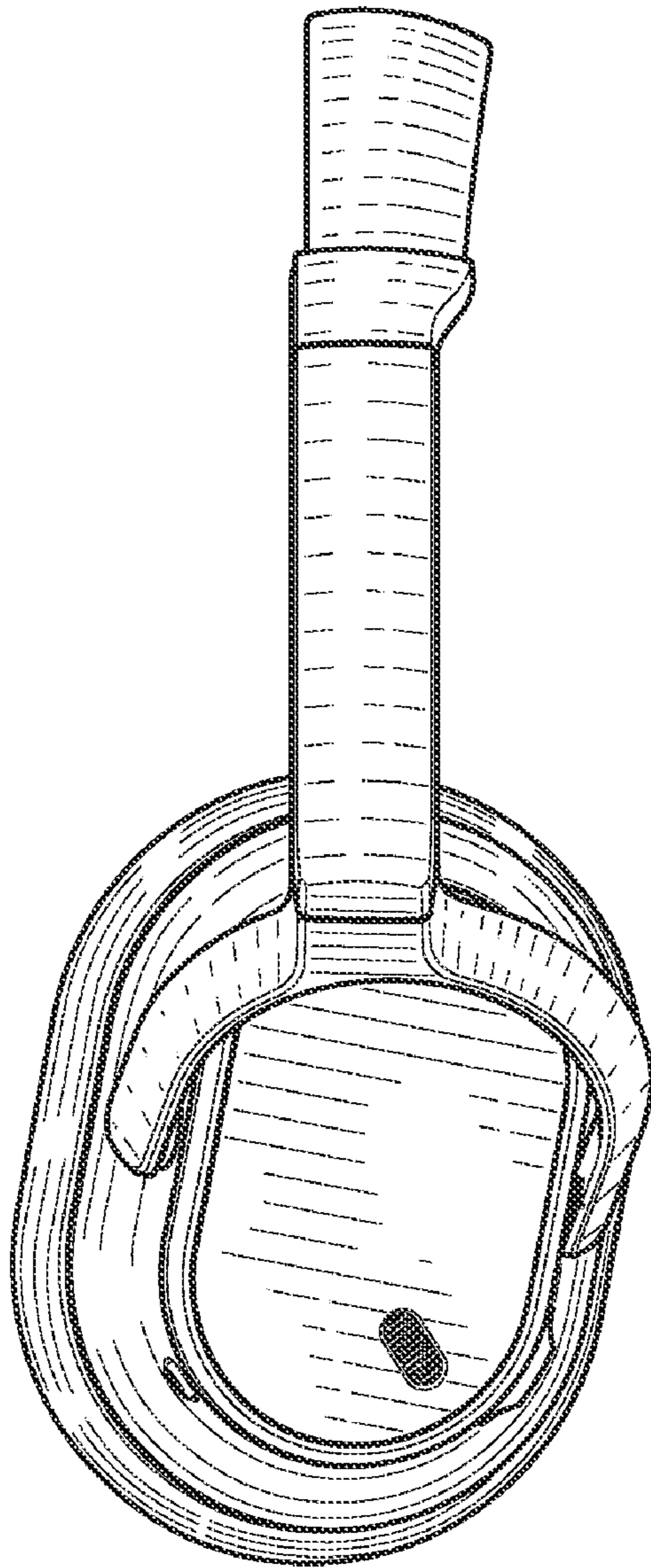


FIG. 4

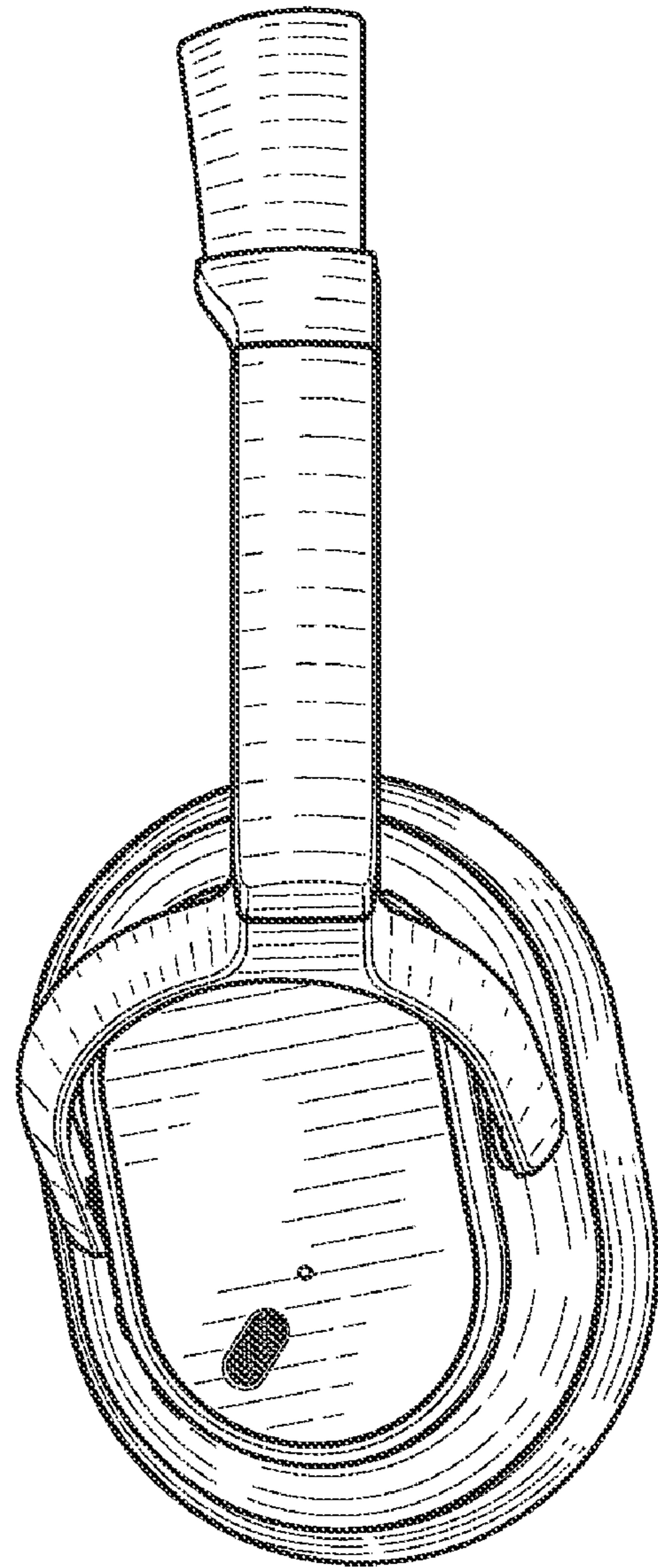


FIG. 5

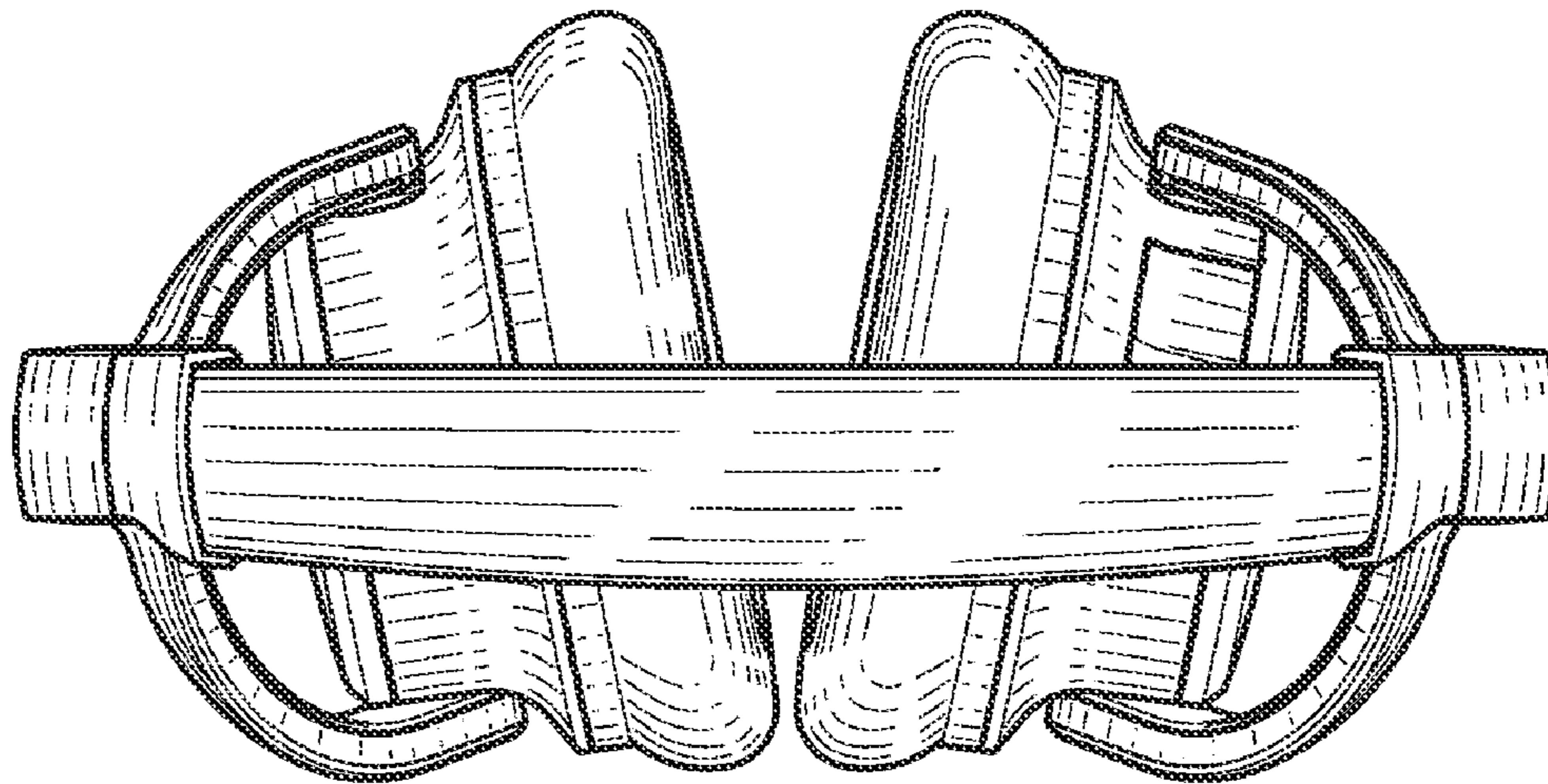


FIG. 6

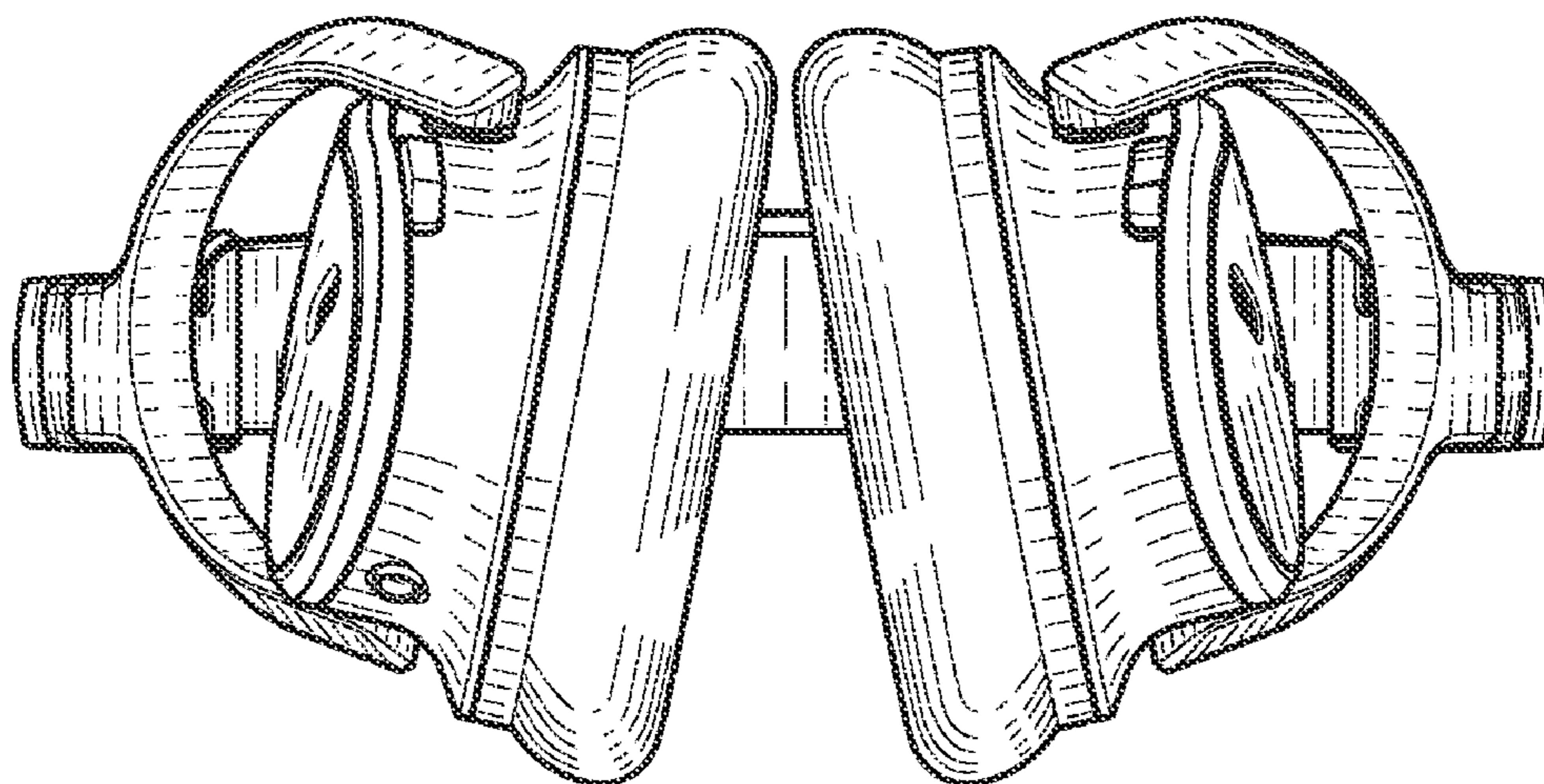


FIG. 7